

INTERNATIONAL DIRECTORY OF IC PACKAGING FOUNDRIES

Directory data was compiled from company inputs and/or website search and may not be current or all-inclusive as of the date of publication.

COMPANY HEADQUARTERS	MANUFACTURING LOCATIONS	PACKAGE TYPES	CONTRACT SERVICES	ASSEMBLY PROCESSES
Company Street Address City, State, Country Telephone Website	Country (Qty) CN = China ID = Indonesia IN = India IT = Italy JP = Japan KR = Korea MX = Mexico MY = Malaysia PH = Philippines PT = Portugal SG = Singapore TH = Thailand TW = Taiwan UK = United Kingdom	Ceramic CB = Ball Array CL = Leads/Pins CN = No Leads Plastic (Molded) PB = Ball Array PL = Leads/Pins PN = No Leads Plastic (No Mold) PC = Cavity/Dam PF = Film/Tape Other WL = Wafer Level	SD = Substrate Design BP = Wafer Bumping WP = Wafer Probing WD = Wafer Dicing WT = Wafer Thinning AS = Assembly FT = Final Test ET = Environmental Test BI = Burn-In	AD = Adhesive/Glass ED = Eutectic/Solder WB = Wire Bond FC = Flip Chip GT = Glob Top MP = Molded Plastic UF = Underfill LP = Lead Plating BA = Ball Attach LA = Lead Attach HS = Hermetic Seal
Advanced Semiconductor Engineering, Inc. No. 26, Chin 3rd Rd., N.E.P.Z. Kaohsiung, Taiwan R.O.C. Tel: +886-7-361-7131 www.aseglobal.com	JP(1), KR (1) MY(1), SG(1) TW(2), US(1)	PB, PL, PN	SD, BP, WP WD, WT AS, FT FT, BI	AD WB, FC MP, UF LP, BA
Advotech Co., Inc. 632 W. 24th Street Tempe, AZ 85282 Tel: +1-480-821-5000 www.advotech.com	US(1)	CB, CL, CN PC	SD, BP WD, AS FT	AD, ED WB, FC GT, UF BA, HS
Amkor Technology Inc.* 1900 S. Price Road Chandler, AZ 85286 Tel: +1-480-821-5000 www.amkor.com	 CN(2), JP(1) KR(3), PH(2) TW(3), SG(2) US(1)	CB, CL, CN PB, PL, PN	SD, BP WD, WT AS, FT ET	AD, ED WB, FC MP, UF, GT LP, BA HS
AmTECH Microelectronics, Inc. 6541 Via Del Oro San Jose, CA 95119 Tel: +1-408-227-8885 www.amtechmicro.com	US(1)	CL, CN PL, PN	SD, WD AS ET	AD, ED WB, GT BA, HS
Aspen Technologies 5050 List Drive, Suite C Colorado Springs, CO 80919 Tel: +1-719-592-9100 www.aspentechologies.net	US(1)	CB, CL, CN PC	SD BP, WD AS	AD, ED WB, FC GT, UF BA, HS
Azimuth Industrial Co., Inc. 30593 Union City Blvd., Suite 110 Union City, CA 94587 Tel: +1-510-441-6000 www.azimuthsemi.com	US(1)	CL, CN PL, PN	WD, AS	AD, ED WB, MP LP, HS
BOS Tech 216 Doha-ri, Mun Beak Myeon, Jin Cheon-gun Chungbuk, 365-861 Korea Tel: +82-43-532-1785	KR(1)	CL PL, PN PF	SD WD, WT AS	AD, ED WB MP LP HS
Carsem (M) Sdn. Bhd. Jalan Lapangan Terbang, P.O. Box 204 30720 Ipoh, Perak, Malaysia Tel: +60-5-312-3333 www.carsem.com	CN(1), MY(2)	CB, CN PB, PL, PN	SD, WP WD, WT AS, FT ET	AD, ED WB, FC MP, UF LP, BA HS


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Catalyst Microtech LLC 5321 Industrial Oaks Blvd., Suite 105 Austin, TX 78735 Tel: +1-512-899-8422 www.catalystmicrotech.com	US(1)	CB, CL, CN PC	WD, AS	AD, ED WB, FC GT, UF BA, HS
Chipbond Technology Corporation No. 3, Li Hsin 5th Rd., Hsinchu Science Park, Hsinchu 300, Taiwan, R.O.C. Tel: +886-3-567-8788 www.chipbond.com.tw	TW(2)	PF	SD BP, WP WD, WT AS, FT ET	AD, FC GT, UF
ChipMOS Taiwan No. 1, R&D Rd. 1, Hsinchu Science Park, Hsinchu 300, Taiwan, R.O.C. Tel: +886-3-577-0055 www.chipmos.com	CN(1), TW(2)	PB, PL, PN PF	SD, BP WD, WT AS, ET	AD, WB FC, UF GT, MP LP, BA
Chip Supply, Inc. 7725 N. Orange Blossom Trail Orlando, FL 32810 Tel: +1-407-298-7100 www.chipsupply.com	US(1)	CB, CL, CN PB, PN, PC, PF WL	SD BP, WP WD, WT AS, FT ET, BI	AD, ED WB, FC GT, UF MP, BA HS
Cirtek Electronics Corporation 116 E. Main Ave., Phase V, SEZ, Laguna Technopark, Binan Laguna, Philippines Tel: +63-49-541-2310 www.cirtek-electronics.com	PH(1)	PL, PN	SD, WP WD, WT AS, FT ET	AD, WB MP, LP HS
Colorado Microcircuits, Inc. 6650 N. Harrison Avenue Loveland, CO 80538 Tel: +1-970-663-4145 www.coloradomicrocircuits.com	US(1)	CB, CL, CN PN, PC	SD WD AS	AD, ED WB, GT MP, HS
Corwil Technology Corporation 1635 McCarthy Blvd. Milpitas, CA 95035 Tel: +1-408-321-6404 www.corwil.com	US(1)	CB, CL, CN PB, PL, PN PC, PF	SD BP, WP WD, WT AS, FT ET, BI	AD, ED WB, FC GT, UF MP, BA HS, LP

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Deca Technologies* 7855 S River Parkway, STE 111 Tempe, AZ 85284 USA Tel: 480 345 9895 www.decatechnologies.com 	PH	WL	SD, WD, WT, FT	BA
EEMS Italia Spa. Viale delle Scienze, 5 02015 Cittaducale Rieti, Italy Tel: +39-07-466-041 ? www.eems.com	CN(1), IT(1) SG(1)	PB, PL, PN	SD, WP WD, WT AS, FT	AD, WB MP, LP BA
Endicott Interconnect Technologies, Inc. Building 258, 1093 Clark Street Endicott, NY 13760 Tel: +1-866-820-4820 www.endicottinterconnect.com	US(1)	PC	SD WD ?, WT ? AS	AD, WB FC, UF GT, BA
Engent, Inc. 3140 Northwoods Pkwy., Suite 300A Norcross, GA 30071 Tel: +1-678-990-3320 www.engentaat.com	US(1)	PB, PN PC	SD, BP WD, WT AS, FT ET	AD, WB FC, UF GT, MP BA
First Level Inc. 3109 Espresso Way York, PA 17402 Tel: +1-717-266-2450 www.firstlevelinc.com	US(1)	CL ?, CN ? PC	SD BP WD AS	AD, ED WB, FC GT, UF BA, LA HS
Formosa Advanced Technologies Co., Ltd. No. 329, Ho-Nan St., Toului, 640 Yunlin, Taiwan R.O.C. Tel: +886-5-557-4888 www.fatc.com.tw	TW(1)	PB, PL	SD, WP WD, WT AS, FT BI	AD, WB MP, LP BA
Greatek Electronics, Inc. No. 136, Gung-Yi Rd., Chunan Cheng, Miaoli Hsien, Taiwan R.O.C. Tel: +886-37-638-568 www.greatek.com.tw	TW(2)	PL, PN	SD, WP WD, WT AS, FT BI	AD, WB MP, LP BA
HANA Semiconductor (Ayutthaya) Co., Ltd. Hi-Tech Industrial Estate Authority of Thailand, 100 Moo 1, T. Baan-Len, A. Bang Pa-In KM. 59 Asia Road, Ayutthaya 13160, Thailand Tel: +66-35-729-300 www.hanagroup.com	CN(1) TH(2) US(1)	PL, PN PF	SD WD, WT AS, FT ET	AD WB, GT MP, LP

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HEI, Inc. 1495 Steiger Lake Lane Victoria, MN 55386 Tel: +1-952-443-2500 www.hei.com	US(3)	CN PB PN PF	SD WD AS	AD, WB FT, UF MP, BA
i2a Technologies 3399 W. Warren Avenue Fremont, CA 94538 Tel: +1-510-770-0322 www.ipac.com	US(1)	PB, PL, PN WL	SD WD, WT AS, FT ET	AD, WB FC, UF MP, LP BA
IC Chip Packaging 13490 TI Blvd., Suite 100 Dallas, TX 75243 Tel: +1-972-470-9290 www.icchippackaging.com	US(1)	PB, PL, PN PC	AS	AD, ED WB, GT BA
IDS Electronics Sdn. Bhd. IDS Park, Seri Iskandar, Bota, Perak, Malaysia Tel: +60-5-371-2288 www.idsesb.com.my	MY(1)	PL PN	WP WD, WT AS, FT ET	AD, WB
Infiniti Solutions Ltd. 122, Middle Road, Midlink Plaza #04-01 Singapore 188973 Tel: +65-6336-0082 www.infinitisolutions.com	PH(1) US(1)	CL, CN PL, PN	SD, WP WD, WT AS, FT	AD, ED, WB MP, LP HS
Interconnect Systems, Inc. 759 Flynn Road Camarillo, CA 93012 Tel: +1-805-482-2870 www.isipkg.com	US(2) MX(1)	PC, PF	SD AS	AD, WB FC, UF GT
Jiangsu Changjiang Electronics Technology Co., Ltd. No. 275, Binjiang Rd., Middle Jiangyin, Jiangsu, China Tel: +86-0510-8685-6417 www.cj-elec.com	CN(3)	PL, PN	WD, WT AS, FT	AD, WB MP, LP
Kingpak Technology Inc. No. 84, Tai-ho Rd., Chu-Pei 302, Hsin-chu Hsien, Taiwan R.O.C. Tel: +886-3-553-5888 www.kingpak.com.tw	TW(1) CN(1)	PB, PN MC	SD WP, WD, WT AS, FT	AD, WB GT, MP BA
King Yuan Electronics Co., Ltd. No. 81, Sec. 2, Gongdaowu Road Hsin-chu 300, Taiwan Tel: +886-3-575-1888 www.kyec.com.tw	TW(4)	n/a	WP, WD, WT FT, BI	n/a
Kyocera America Inc. 8611 Balboa Avenue San Diego, CA 92123 Tel: +1-858-576-2600 http://americas.kyocera.com/kai/semiparts	US(1)	CB, CL, CN PB, PL	SD WD, WT AS, ET	AD, ED WB, FC UF, GT LP, BA HS

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Linwave Technology Ltd. Digitek House, Whisby Way, Lincoln Lincolnshire, England, UK LN6 3LQ Tel: +44-1522-681-811 www.linwave.co.uk	UK(1)	CL, CN PC	WD AS FT	AD, ED WB GT HS
Lingsen Precision Industries Ltd. 5-1, Nan 2nd Road, T.E.P.Z. Taichung 42701 Taiwan R.O.C. Tel: +886-4-2533-5120 www.lingsen.com.tw	TW(2)	PB, PL, PN MC	SD, WP WD, WT AS, FT ET	AD, WB MP, LP BA
Majelac Technologies, Inc. 262 Bodley Road Aston, PA 19014 Tel: +1-610-459-8786 www.majelac.com	US(1)	CL, CN PB, PL, PN PC	SD WD AS	AD WB, FC GT, MP, UF BA, HS
Maxtek Components Corporation 2905 SW Hocken Avenue Beaverton, OR 97005 Tel: +1-503-627-4521 www.maxtek.com	US(3)	CL, PN PB	SD WP, WD AS, FT ET, BI	AD, ED WB, FC MP, UF BA, HS
Microelectronic Assembly Frankfurt(Oder) GmbH Otto-Hahn-Strasse 24 Frankfurt(Oder) 15236, Germany Tel: +49-335-387-1963 www.maf-ffo.de	DE(1)	CL, CN PL, PN PC	WD AS	AD, WB MP, LP
Microelectronic Packaging Dresden GmbH Grenzstrasse 22 Dresden 01109, Germany Tel: +49-351-213-6100 www.mpd.de	DE(1)	CL, CN PL, PN PC	WD, WT AS	AD, WB FC, UF GT, BA
Millennium Microtech Thailand* 17/2 Moo 18, Suwintawong Rd., Tambon, Saladang, Bannumprieliu, Chacherngsao 24000, Thailand Tel: +66-38-845-530 www.m-microtech.com	 TH(1)	CL, PL, PN	SD, WP WD, WT AS, FT ET, BI	AD, ED WB, MP LP, HS
NANIUM S.A Avenida 1º de Maio 801, 4485-629 Vila do Conde, Portugal Tel: +351-252-246-000 www.nanium.com	 PT(1)	PB, PC PL, PN WL, MC	SD, BP WP, WD, WT AS, FT ET, BI	AD, WB FC, UF GT, MP LP, BA ED
Optocap, Ltd. 5 Bain Square Livingston, Scotland, UK EH54 7DQ Tel: +44-1506-403-550 www.optocap.com	UK(1)	CL, CN	SD, WD AS, ET	AD, ED WB, FC GT, UF, MP BA, HS


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Orient Semiconductor Electronics No. 9, Central 3rd Street, N.E.P.Z., Kaohsiung 811 Taiwan R.O.C. Tel: +886-7-361-3131 www.ose.com.tw	TW(1) PH(1)	PB PL, PN	SD, WP WD, WT AS, FT ET, BI	AD, WB FC, UF MP, LP
Pantronix Corporation 2710 Lakeview Court Fremont, CA 94538 Tel: +1-510-656-5898 www.pantronix.com	CN(1) PH(2) US(1)	CL, CN PB, PL, PN PC	SD WD, WT AS, FT ET	AD, ED WB, MP FC, UF LP, BA HS
Powertech Technology Inc. No. 26, Datong Rd., Hsinchu Industrial Park, Hukou, Hsinchu 30352 Taiwan R.O.C. Tel: +886-3-598-0300 www.pti.com.tw	CN(1) TW(3)	PB, MC PL, PN	SD, WP WD, WT AS, FT ET, BI	AD, WB MP, LP BA
Promex Industries, Inc. 3075 Oakmead Village Drive Santa Clara, CA 95051 Tel: +1-408-496-0222 www.promex-ind.com	US(1))	CL, CN PL, PN PC	SD, WD AS, ET	AD, ED WB, MP FC, UF GT, HS
Psi Technologies, Inc. Electronics Ave., FTI Special Economic Zone, Taguig Metro Manila, Philippines Tel: +63-2-838-4966 www.psistechnologies.com	PH(2)	CL, CN PL, PN	SD, WD AS, FT ET	AD, ED WB, MP LP, HS
<div>Quik-Pak* 10987 Via Frontera San Diego, CA 92127 Tel: +1-858-674-4676 www.icproto.com</div> <div></div>	US(1)	CL, CN PB, PL, PN PC, PF	WD, WT AS, ET BP	AD, ED WB, GT FC, UF BA, MP LP, HS
Semi-Pac Inc. 1206 #F Mt. View Alviso Road Sunnyvale, CA 94089 Tel: +1-408-734-3832 www.semipac.com	US(1)	CL, CN PC	WD AS	AD, WB GT, HS
Sencio BV Microweg 1-11 6545 CL Nijmegen, The Netherlands Tel: +31-24-371-4499 www.sencio.nl	NL(1)	PL, PN	WD, WT AS	AD, ED, WB FC, UF GT, MP

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Signetics Corporation 483-3 Buphung-ri, Thanh-yun-myun, Paju-si Gyungki-do, Korea 413-840 Tel: +82-31-940-7660 www.signetics.com	KR(2)	CB, PB PL, PN	SD, WP WD, WT AS, FT ET	AD, WB FC, UF MP, LP BA
Sigurd Microelectronics Company No. 436, Sec. 1, Pei-Shing Rd., Chu-Tung Hsin-chu, Taiwan R.O.C. Tel: +886-3-595-9213 www.sigurd.com.tw	CN(1) TW(3)	CN PL, PN	SD, WP WD, WT AS, FT ET, BI	AD, WB MP, LP
Silicon Turnkey Systems* 801 Buckeye Court Milpitas, CA 95035 Tel: +1-408-432-1790 www.siliconturnkey.com	 US(1)	CL, CN PC	WP, WD AS, FT ET, BI	AD, ED WB, FC GT, UF HS
Siliconware Precision Industries Co., Ltd. No. 123, Sec. 3, Da Fong Rd., Tan tzu, Taichung 427, Taiwan R.O.C. Tel: +886-4-2534-1525 www.spil.com.tw	CN(1) TW(3)	CN PB, PL, PN PF WL	SD, BP WP WD, WT AS, FT ET	AD WB, FC MP, UF LP, BA
Solitron Devices, Inc. 3301 Electronics Way West Palm Beach, FL 33407 Tel: +1-561-848-4311 www.solitrondevices.com	US(1)	CN PL, PN	SD, WD AS, FT ET	AD, ED WB, MP HS
SPEL Semiconductor Ltd. 5 CMDA Industrial Estate, MM Nagar (Chennai) 603209, India Tel: +91-44-4740-5473 www.spel.com	IN(1)	PL, PN	SD, WP WD, WT ? AS, FT ET	AD, WB MP, LP
Stars Microelectronics (Thailand) Public Co., Ltd. 605-606 Moo 2, EPZ, Bang Pa-In Industrial Estate, Klongjig, Bang Pa-In, Ayutthaya 13160, Thailand Tel: +66-35-221-777 www.starsmicroelectronics.com	TH(2)	PL, PN	SD, WD AS, FT ET	AD, WB MP, LP
STATS-ChipPAC Ltd. 10 Ang Mo Kio Street 65, #05-17/20 Technopoint, Singapore 569059 Tel: +65-6824-7777 www.statschippac.com	CN(1), KR(1) MY(1), SG(1) TH(1), TW(1) US(2)	PB, PL, PN WL	SD, BP WP, FT WD, MT AS, ET	AD, WB FC, UF MP, LP BA

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Taiwan IC Packaging Corporation 2, South 3 Road, Kaohsiung Export Processing Zone Kaohsiung, Taiwan R.O.C. Tel: +886-7-815-8800 www.ticp.com.tw	TW(1)	PL, PN MC	SD, WD AS, FT	AD, WB MP, LP
Taiwan Micropaq Corporation No. 4, Wenhua Rd., Hsinchu Science Park, Hu-kou, Taiwan R.O.C. Tel: +886-3-597-9402 www.tmc.com.tw	TW(3)	PB, PL, PN MC	SD, WP WD, WT AS, FT ET	AD, WB MP, LP BA
Team Pacific Corporation Electronics Ave., FTI Complex Taguig City 1630, Philippines Tel: +63-2-838-5005 www.teamglac.com	PH(1)	CN PL	SD WD AS, FT ET	AD, WB MP, LP HS
Tong Hsing Electronic Industries, Ltd. 55, Lane 365, Yingtao Road, Yinko, Taipei Hsien, Taiwan R.O.C. Tel: +886-2-2679-0122 www.theil.com	PH(1) TW(1)	CN PB	SD, WP WD, WT AS, FT ET	AD, ED WB, MP FC, UF BA, HS
Unisem (M) Berhad 9th Floor, UBN Tower, No. 10 Jalan P. Ramlee, 50250 Kuala Lumpur, Malaysia Tel: +60-3-2072-3760 www.unisemgroup.com	CN(1), ID(1) MY(1), UK(1) US(1)	PB, PL, PN WL	SD, BP WP, WD, WT AS, FT ET, BI	AD, WB FC, UF MP, LP BA
United Test & Assembly Center Ltd. 5 Serangoon North Ave 5 Singapore 554916 Tel: +65-6481-0033 www.utacgroup.com	CN(3), SG(2) TH(1), TW(1)	PB, PL, PN WL, MC	SD, WP WD, WT AS, FT ET, BI	AD, WB FC, UF MP, GT LP, BA
Vigilant Technology Co., Ltd. Ladkrabang Industrial Estate, Export Processing Zone 3, 322 Moo 4 Chalokkrung Rd., Laplatiew, Ladkrabang, Bangkok 10520, Thailand Tel: +66-2-739-6203 www.vigilant-techno.com	TH(1)	PL	SD WD, AS FT, ET	AD, WB MP, LP
VLSIP Technologies Inc. 750 Presidential Drive Richardson, TX 75081 Tel: +1-972-437-5506 www.vlsip.com	US(1)	PB, PL, PN PC	SD, WD AS, FT ET	AD, ED WB, FC GT, UF, MP BA, HS
Walton Advanced Engineering, Inc. No. 18, North First Road, K. E. P. Z. Kaohsiung 806, Taiwan R.O.C. Tel: +886-7-811-1330 www.walton.com.tw	CN(1) JP(1) TW(1)	PB, PL	SD, WP WD, WT AS, FT ET, BI	AD, WB MP, LP BA